## Special Compendium on the 2024 IEEE 6<sup>th</sup> International Conference on DC Microgrids (ICDCM2024)

Deadline for Manuscript Submissions: 1 November 2024 Scheduled Publication Time: 08.2025

Papers that show the latest advancements in dc grid technologies and applications. The scope encompasses aspects of power electronics, system architectures, controls, protection, intelligent system management, energy storage, and ac grid interfaces that are unique to dc microgrids. Topics of interest include, but are not limited to:

- Low- and medium-voltage dc grids and utility services
- Low- and medium-voltage dc infrastructure for residential, commercial, and industrial sectors
- Low- and medium-voltage dc charging of light and heavy vehicles
- Off-grid microgrids
- Low-cost technologies for community microgrids
- Distributed energy resources in dc microgrids
- DC interfaces for energy storage
- Modeling, stability, control, and optimization of dc systems
- Reliable, resilient, and reconfigurable dc systems
- EMI and power quality in dc systems
- Grounding and human safety issues unique to dc systems
- Fault detection and protection
- Standards and policies for dc components and systems
- New technologies for managing dc microgrids
- New components and devices for dc systems
- Converters for interlinking dc with ac systems and multiport systems
- Other novel topics relevant to dc microgrids

We will accept selected full journal articles of contributions already accepted at the IEEE 6th International Conference on DC Microgrids (ICDCM2024). A paper submission is still expected to include a literature review to establish its relationship to prior work, and present sufficient results to prove the validity and viability of proposed concepts.

All manuscripts must be submitted through Manuscript Central at <a href="https://mc.manuscriptcentral.com/oj-pel">https://mc.manuscriptcentral.com/oj-pel</a>. Submissions must be marked "ICDCM 2024 Special Compendium" on the cover page. When uploading your paper, please select the corresponding manuscript type for the special compendium. Please refer to <a href="https://www.ieee-pels.org/">https://www.ieee-pels.org/</a> for general information about submitting through Manuscript Central.

<b>Guest Editors</b>	<b>Guest Associate Editors</b>	Proposed Timeline
Enrico Santi, University of South Carolina, USA	Pavol Bauer, TUDelft, The Netherlands	11.01.24: submission deadline 02.01.25: 1 <sup>st</sup> round notification
Dong Dong, Virginia Tech, USA	<b>Dmitri Vinnikov</b> , Tallinn University of Technology, Estonia	03.01.25: major revision deadline
	Tommaso Caldognetto, University of Padova, Italy Yunwei (Ryan) Li, University of Alberta, Canada	<ul> <li>04.01.25: 2<sup>nd</sup> round notification</li> <li>06.01.25: forwarded to IEEE for publication</li> <li>08.01.25: articles in OJ-PEL</li> </ul>
	Qing Liu, Hebei University of Technology, China	
	Lisa Qi, ABB Inc., USA	